# XN04404 (XN4404)

## Silicon PNP epitaxial planar type

## For general amplification

### ■ Features

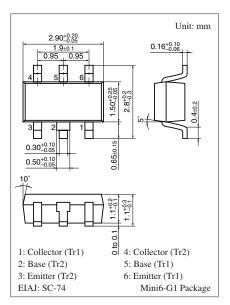
- Two elements incorporated into one package
- Reduction of the mounting area and assembly cost by one half

### ■ Basic Part Number

• 2SB0970 (2SB970) × 2

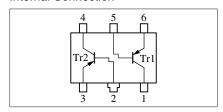
## ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol Rating		Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	-15	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-10	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	-7	V	
Collector current	$I_C$	- 0.5	A	
Peak collector current	$I_{CP}$	-1	A	
Total power dissipation	$P_{T}$	300	mW	
Junction temperature	$T_{j}$	150	°C	
Storage temperature	$T_{stg}$	-55 to +150	°C	



Marking Symbol: CV

#### Internal Connection



## ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

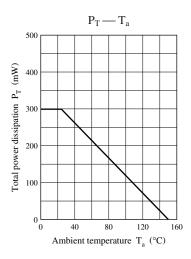
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = -10 \mu A, I_E = 0$	-15			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = -1 \text{ mA}, I_B = 0$	-10			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = -10 \ \mu A, I_C = 0$	-7			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = -10 \text{ V}, I_{E} = 0$			- 0.1	μΑ
Forward current transfer ratio *	h <sub>FE1</sub>	$V_{CE} = -2 \text{ V}, I_{C} = -500 \text{ mA}$	100		350	_
	h <sub>FE2</sub>	$V_{CE} = -2 \text{ V}, I_{C} = -1 \text{ A}$	60			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -400 \text{ mA}, I_B = -8 \text{ mA}$		- 0.16	- 0.30	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	$I_C = -400 \text{ mA}, I_B = -8 \text{ mA}$		- 0.8	-1.2	V
Transition frequency	$f_T$	$V_{CB} = -10 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		130		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		22		pF
(Common base, input open circuited)						

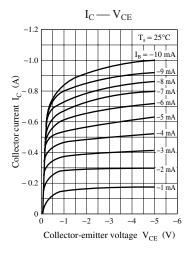
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

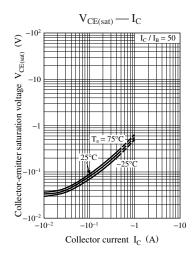
2. \*: Pulse measurement

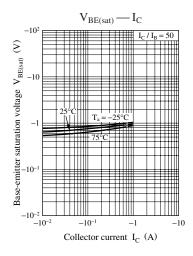
Note) The part number in the parenthesis shows conventional part number.

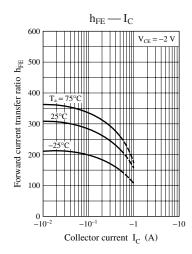
## **Panasonic**

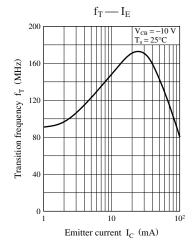


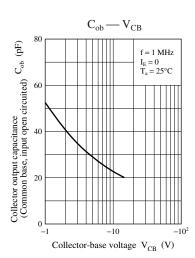












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